Title (en)

MOBILE DEVICE, EXPOSURE DEVICE, EXPOSURE METHOD, MICRO-MOTION BODY, AND DEVICE MANUFACTURING METHOD

Title (de)

MOBILE EINRICHUNG, BELICHTUNGSEINRICHTUNG, BELICHTUNGSVERFAHREN, MIKROBEWEGUNGKÖRPER UND BAUELEMENTEHERSTELLUNGSVERFAHREN

Title (fr)

DISPOSITIF MOBILE, DISPOSITIF D'EXPOSITION, PROCEDE D'EXPOSITION, CORPS A DEPLACEMENT MICROMETRIQUE ET PROCEDE DE FABRICATION DE DISPOSITIFS

Publication

EP 2006884 A2 20081224 (EN)

Application

EP 07715038 A 20070228

Priority

- JP 2007053723 W 20070228
- JP 2006095982 A 20060330

Abstract (en)

Power-transmitting, waste-heat frames (24A, 24B) can continually absorbs heat radiated from wafer stages (WST1, WST2), and therefore it becomes possible to suppress adverse influence on exposure accuracy due to the heat generated at the wafer stages (WST1, WST2). In this case, unlike the conventional method, it is not necessary to connect a conduit (tube) for supplying coolant to the wafer stages (WST1, WST2) from the outside, and accordingly declines in movement accuracy of the wafer stages (WST1, WST2) due to tension of such a conduit can be prevented. Also from this standpoint, the exposure accuracy can be maintained at high accuracy.

IPC 8 full level

H01L 21/027 (2006.01); **G03F 7/20** (2006.01); **H01L 21/68** (2006.01)

CPC (source: EP KR US)

G03F 7/70425 (2013.01 - KR); **G03F 7/70716** (2013.01 - EP KR US); **G03F 7/70725** (2013.01 - KR); **G03F 7/70758** (2013.01 - EP KR US); **G03F 7/70858** (2013.01 - EP KR US); **H01L 21/67109** (2013.01 - KR); H01L 21/67109 (2013.01 - EP US)

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

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US 2007273860 A1 20071129; **US 7696653 B2 20100413**; CN 101410949 A 20090415; EP 2006884 A2 20081224; EP 2006884 A4 20100818; EP 2006884 A9 20090715; JP 2013149996 A 20130801; JP 5257845 B2 20130807; JP 5725059 B2 20150527; JP WO2007113955 A1 20090813; KR 101531801 B1 20150625; KR 20090009800 A 20090123; KR 20140041932 A 20140404; TW 200736859 A 20071001; TW I454859 B 20141001; WO 2007113955 A1 20071011

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US 71224307 A 20070227; CN 200780011066 A 20070228; EP 07715038 A 20070228; JP 2007053723 W 20070228; JP 2008508463 A 20070228; JP 2013046987 A 20130308; KR 20087024702 A 20081009; KR 20147005802 A 20070228; TW 96105249 A 20070213